## PATENT ASSIGNMENT

# Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

## **CONVEYING PARTY DATA**

Name	Execution Date
Young Sub Jin	12/23/2010
So Young Kwon	12/23/2010
Sung Kwan Kim	12/23/2010
Hwan Seok Park	12/23/2010
Jae Keun Hong	12/23/2010
Byeong Do Lee	12/23/2010
Chul In Lim	12/23/2010

### **RECEIVING PARTY DATA**

Name:	Cheil Industries Inc.	
Street Address:	290 Gongdan-dong	
Internal Address:	Gumi-si	
City:	Gyeongsangbuk-do	
State/Country:	REPUBLIC OF KOREA	
Postal Code:	730-710	

## PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12979448

## **CORRESPONDENCE DATA**

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PATENT

REEL: 025541 FRAME: 0176

JF \$40.00 129/9448

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ATTORNEY DOCKET NUMBER:	6250.165
NAME OF SUBMITTER:	Melissa B. Pendleton
Total Attachments: 5 source=AssignmentsUSPTO#page1.tif source=AssignmentsUSPTO#page2.tif source=AssignmentsUSPTO#page3.tif source=AssignmentsUSPTO#page4.tif source=AssignmentsUSPTO#page5.tif	

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RECORDATION FORM COVER SHEET					
PATENTS ONLY					
To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.					
1. Name of conveying party(ies) 1) Young Sub Jin 6) Byeong Do Lee 2) So Young Kwon 7) Chul In Lim	2. Name and address of receiving party(ies) Name: Cheil Industries Inc.				
3) Sung Kwan Kim 4) Hwan Seok Park	Internal Address:				
5) Jae Keun Hong Additional name(s) of conveying party(ies) attached? Yes X No	290 Gongdan-dong				
3. Nature of conveyance/Execution Date(s):  Execution Date(s) December 23, 2010	Street Address: 290 Gongdan-dong				
X Assignment Merger					
Security Agreement Change of Name	City: Gumi-si				
Joint Research Agreement	<sub>State:</sub> Gyeongsangbuk-do				
Government Interest Assignment	Country: South Korea Zip: 730-710				
Executive Order 9424, Confirmatory License					
Other	Additional name(s) & address(es) attached? Yes 🗶 No				
A. Patent Application No.(s) 12/979,448	document is being filed together with a new application.  B. Patent No.(s)  B. Patent No.(s)				
5. Name and address to whom correspondence	6. Total number of applications and patents				
concerning document should be mailed:	involved: 1				
Name: Summa, Additon & Ashe, P.A.	7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00				
Internal Address:	Authorized to be charged by credit card				
	Authorized to be charged to deposit account				
Street Address: 11610 N. Community House	Enclosed				
Road, Suite 200	None required (government interest not affecting title)				
City: Charlotte	8. Payment Information				
State: NC Zip: 28277-2199	a. Credit Card Last 4 Numbers Expiration Date				
Phone Number: 704-945-6700					
Fax Number: 704-945-6735	b. Deposit Account Number				
Email Address:	Authorized User Name				
9. Signature: /Melissa B. Pendleton/	December 28, 2010				
Signature Melissa B. Pendleton	Date				
Name of Person Signing	Total number of pages including cover sheet, attachments, and documents:				

Documents to be recorded (including cover sheet) should be faxed to (571) 273-0140, or mailed to:
Mail Stop Assignment Recordation Services, Director of the USPTO, P.O.Box 1450, Alexandria, V.A. 22313-1450

#### ASSIGNMENT

WHEREAS, I, Young Sub Jin, a citizen of the Republic of Korea, with a mailing address of Cheil Industries Inc., 332-2, Gocheon-dong, Uiwang-si, Gyeonggi-do, Republic of Korea; So Young Kwon, a citizen of the Republic of Korea, with a mailing address of Cheil Industries Inc., 332-2, Gocheon-dong, Uiwang-si, Gyeonggi-do, Republic of Korea; Sung Kwan Kim, a citizen of the Republic of Korea, with a mailing address of Cheil Industries Inc., 332-2, Gocheon-dong, Uiwang-si, Gyeonggi-do, Republic of Korea; Hwan Seok Park, a citizen of the Republic of Korea, with a mailing address of Cheil Industries Inc., 332-2, Gocheon-dong, Uiwang-si, Gyeonggi-do, Republic of Korea; Jae Keun Hong, a citizen of the Republic of Korea, with a mailing address of Cheil Industries Inc., 332-2, Gocheon-dong, Uiwang-si, Gyeonggi-do, Republic of Korea; Byeong Do Lee, a citizen of the Republic of Korea, with a mailing address of Cheil Industries Inc., 332-2, Gocheon-dong, Uiwang-si, Gyeonggi-do, Republic of Korea; and Chul In Lim, a citizen of the Republic of Korea, with a mailing address of Cheil Industries Inc., 332-2, Gocheon-dong, Uiwang-si, Gyeonggi-do, Republic of Korea (hereinafter referred to as "ASSIGNOR"), am a joint inventor of certain new and useful improvements (hereinafter collectively referred to as "INVENTION") in Weatherable Thermoplastic Resin Composition Having Excellent Low Gloss Characteristic and Method of Preparing the Same, for which an application for United States Letters Patent is being filed concurrently herewith and which application claims priority from a Korean Application No. 10-2009-0136011,

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filed December 31, 2009, all applications listed above being hereinafter referred to as the "APPLICATION"; and

WHEREAS, Cheil Industries Inc., a Korean corporation, having a principal place of business at 290 Gongdan-dong, Gumi-si, Gyeongsangbuk-do 730-710, Republic of Korea, (hereinafter referred to as "ASSIGNEE") has acquired the equitable right, title, and interest—and is desirous of acquiring any remaining right, title, and interest—in and to said INVENTION as described in said APPLICATION, and in and to any and all Letters Patent that shall be granted with respect to said INVENTION in the United States of America and all foreign countries;

NOW, THEREFORE, be it known that for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I, the ASSIGNOR, have sold, assigned, transferred, and conveyed unto said ASSIGNEE, its successors and assigns, my equitable right, title, and interest-and by these presents do hereby sell, assign, transfer, and convey unto said ASSIGNEE, its successors and assigns any remaining right, title, and interest-in and to said INVENTION and APPLICATION, in and to any and all continuations, continuations-in-part, or divisions thereof, and in and to any and all Letters Patent of the United States of America and all foreign countries or reissues, reexaminations, or extensions thereof that may be granted therefore or thereon, for the full term for which said Letters Patent may be granted, together with the right to claim the priority of said APPLICATION in all foreign countries in accordance with international treaties and conventions, the same to be held and enjoyed by said ASSIGNEE, its successors and assigns, as

fully and entirely as the same would have been held and enjoyed by me if an assignment and sale had not been made.

I acknowledge that at the time the INVENTION was made, the INVENTION was subject to an obligation of assignment to said ASSIGNEE. I further acknowledge that said ASSIGNEE has the sole right to determine patent prosecution strategies with respect to said INVENTION and all corresponding applications, and hereby request that Letters Patent be issued in accordance with this assignment.

I further covenant and agree to bind my heirs, legal representatives, and assigns, promptly to communicate to said ASSIGNEE or its representatives any facts known to me relating to said INVENTION, to testify in any interference or legal proceedings involving said INVENTION, to execute any additional papers that may be requested to confirm the right of the ASSIGNEE, its representatives, successors or assigns to secure patent or similar protection for said INVENTION in all countries and to vest in the ASSIGNEE complete title to said INVENTION and Letters Patent, without further compensation, but at the expense of said ASSIGNEE, its successors, assigns and other legal representatives.

IN WITNESS WHEREOF, I have hereunto signed my name on the day and year set forth below.

12 /23, 2010	진 성 과
12/23, 2010	Hwan Seok Park
12 /23, 2010	Jae Keun Hong
12/25, 2010	O   (P) Z Bycong Do Lee
(2/23, 2010	OLENO Chul In Lim

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**RECORDED: 12/28/2010**